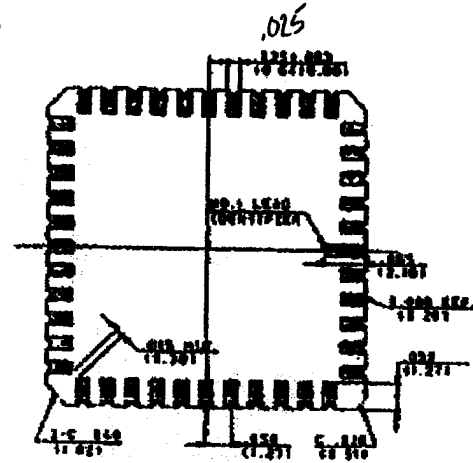
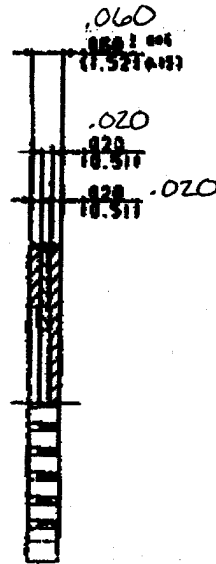
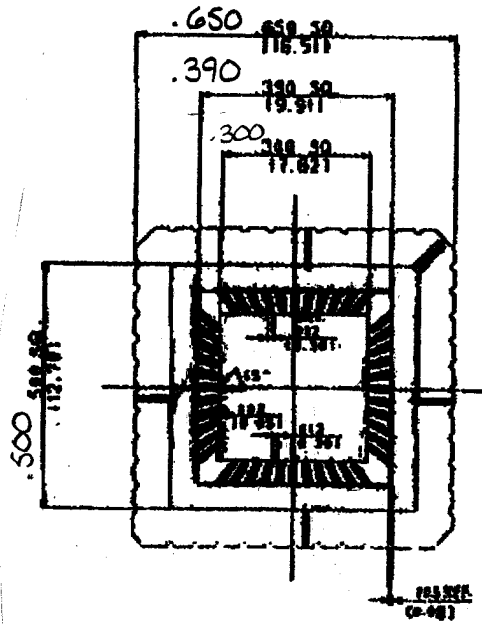


SSM P/N LCC04417



A:EDGE CASTELLATION- .005-.022
16.75-9.501
B:EDGE CASTELLATION- .002-.015
16.10-9.301



NOTES

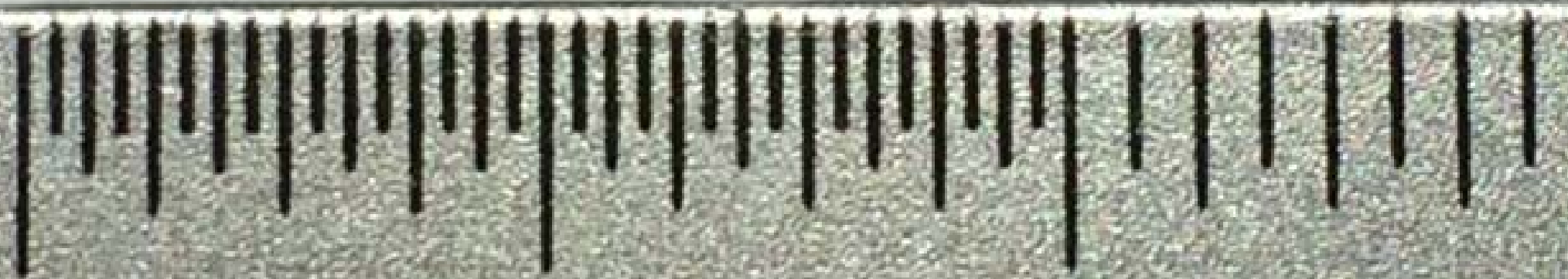
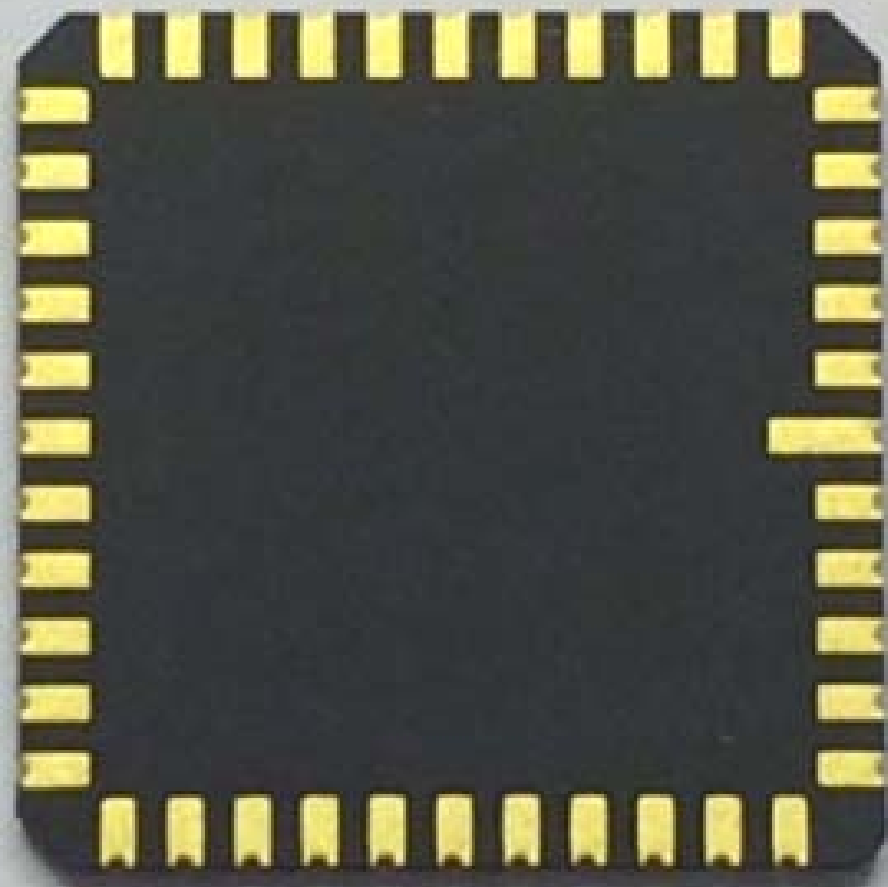
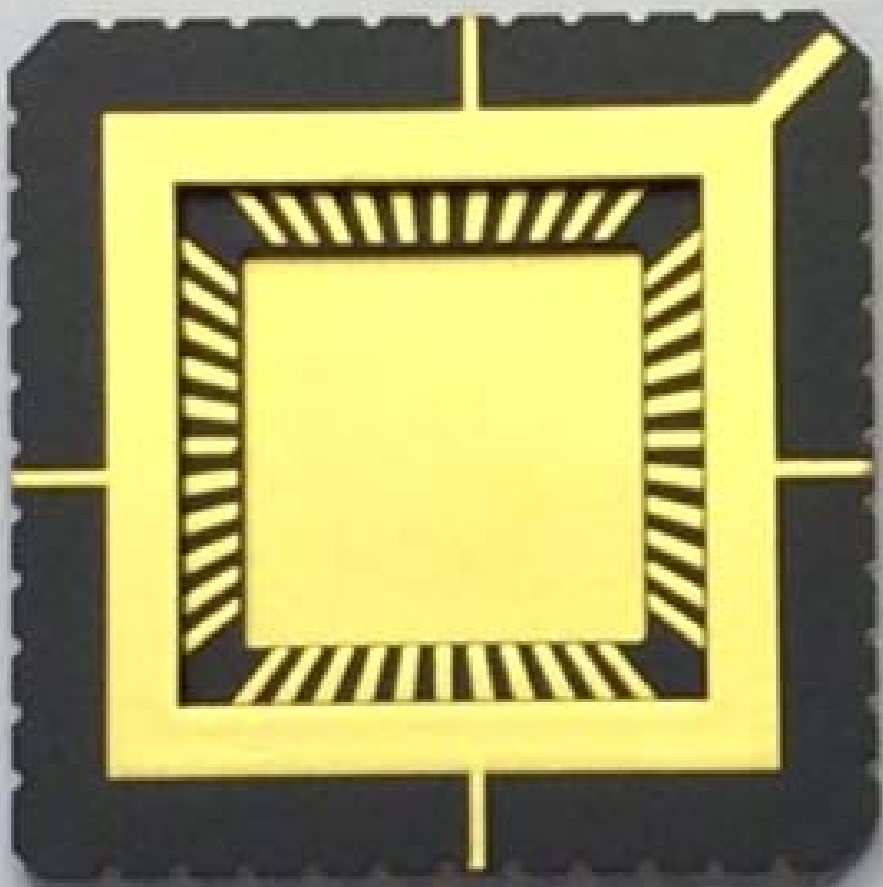
1. TOLERANCE: ±1% N.L.T. ±.005 (0.13)
2. ALL EXPOSED METALLIZATION AREAS SHALL BE GOLD PLATED 60 MICRO INCHES MIN. OVER ELECTROPLATED NICKEL 90 TO 250 MICRO INCHES.

SCALE	INTERNAL DRAGS	REV	%	FILE
2:1	INTERNAL DRAGS	1	NEW	EA LEAD CHIP CARRIER
DESCRIPTION	FUNCTION		GROUP	OWN PART NO.
INCH (mm)	3:20			214558
APPROVED	DESIGN	CHECKED	DESIGNED	DATE
J. O. ...	M. ...	P. ...	S. ...	11-00576-801
Dec 28-87	Dec 28-87	Dec 28-87	Dec 28-87	CUSTOMER DRWG NO.
				MCB-50744A



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0 inch

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